

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S365	15	standoff.clm. and solder.clm. and (melting adj temperature).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:45
S366	10	standoff.clm. and solder.clm. and ((melting adj temperature) near5 (higher or lower or greater)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:46
S367	10	standoff.clm. and solder.clm. and ((melting adj temperature) near10 (higher or lower or greater)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:46
S368	4	standoff.clm. and solder.clm. and ((melting adj temperature) near10 (higher or lower or greater)).clm. and degree.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:47

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S343	13909	((melting adj temperature) near10 (lower or higher))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:32
S344	1808	((melting adj temperature) near10 (lower or higher)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:32
S345	39	((melting adj temperature) near10 (lower or higher)).clm. and ((melting adj temperature) near5 degree).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:32
S346	49	((melting adj temperature) near10 (lower or higher)).clm. and ((melting adj temperature) near10 degree).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:34
S347	16	((melting adj temperature) near10 (lower or higher)).clm. and ((melting adj temperature) near10 degree).clm. and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:34
S348	15	((melting adj temperature) near10 (lower or higher)).clm. and ((melting adj temperature) near10 degree).clm. and solder.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:34

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S34 3	13909	((melting adj temperature) near10 (lower or higher))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:32
S34 4	1808	((melting adj temperature) near10 (lower or higher)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:32
S34 5	39	((melting adj temperature) near10 (lower or higher)).clm. and ((melting adj temperature) near5 degree).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:32
S34 6	49	((melting adj temperature) near10 (lower or higher)).clm. and ((melting adj temperature) near10 degree).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:34
S34 7	16	((melting adj temperature) near10 (lower or higher)).clm. and ((melting adj temperature) near10 degree).clm. and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:34
S34 8	15	((melting adj temperature) near10 (lower or higher)).clm. and ((melting adj temperature) near10 degree).clm. and solder.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:34

S35 0	36	S349 and (melting adj temperature).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:36
S35 1	24	S349 and ((melting adj temperature) near5 (higher or lower or greater)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:36
S35 2	9	S349 and ((melting adj temperature) near5 (higher or lower or greater)).clm. and ((melting adj temperature) near10 degrees)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:39
S35 3	10	S349 and ((melting adj temperature) near5 (higher or lower or greater)).clm. and ((temperature) near10 degrees)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:39
S35 4	9	S349 and ((melting adj temperature) near5 (higher or lower or greater)).clm. and ((temperature) near10 degrees).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:39
S35 5	0	S349 and ((melting adj temperature) near5 (higher or lower or greater)).clm. and ((temperature) near10 degrees).clm. and (attachment).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:39
S35 6	1	((melting adj temperature) near5 (higher or lower or greater)).clm. and ((temperature) near10 degrees).clm. and (attachment).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:39

S358	20	S357 and degree.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:40
S359	17	S357 and degree.clm. and (melting adj temperature).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:42
S360	0	S357 and degree.clm. and (melting adj temperature).clm. and capacitor.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:42
S361	2	S357 and (melting adj temperature).clm. and capacitor.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:44
S362	0	S357 and ((melting adj temperature) near10 degree).clm. and capacitor.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:43
S363	0	S357 and ((melting adj temperature) near10 degree).clm. and capacitor.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:43
S364	3	S357 and (melting adj temperature).clm. and capacitor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:44
S365	15	standoff.clm. and solder.clm. and (melting adj temperature).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:45
S366	10	standoff.clm. and solder.clm. and ((melting adj temperature) near5 (higher or lower or greater)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:46
S367	10	standoff.clm. and solder.clm. and ((melting adj temperature) near10 (higher or lower or greater)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:46

S36 8	4	standoff.clm. and solder.clm. and ((melting adj temperature) near10 (higher or lower or greater)).clm. and degree.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:47
S36 9	20	S357 and degree.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:49
S37 0	15	S357 and (degree near10 (standoff or solder)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:49
S37 1	12	S357 and (melting adj temperature) near10 (degree near10 (standoff or solder)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:51
S37 2	2	S357 and (melting adj temperature) near10 (degree near10 (standoff or solder)).clm. and ((melting adj temperature) near10 (attachment or pad)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:52
S37 3	3	S357 and (melting adj temperature) near10 (degree near10 (standoff or solder)) and ((melting adj temperature) near10 (attachment or pad))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:53
S37 4	22	(melting adj temperature) near10 (degree near10 (standoff or solder)) and ((melting adj temperature) near10 (attachment or pad))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:53

S37 6	47	S375 and (melting adj temperature).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:55
S37 7	69	S375 and (melting adj (point or temperature)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:56
S37 8	50	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:56
S37 9	15	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:57
S38 0	6	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and ((melting adj (temperature or point)) near5 degree)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:58
S38 1	6	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and ((temperature or point) near5 degree)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:58
S38 2	6	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and ((temperature or point) near10 degree)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:58
S38 3	5	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and degree. clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:59

S38 4	0	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and celcius. clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 09:59
S38 5	15	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 10:00
S38 6	11	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and (melting near10 (lower or higher or greater)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 10:02
S38 7	6	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and (melting near10 (lower or higher or greater)).clm. and degree	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 10:03
S38 8	5	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and (melting near10 (lower or higher or greater)).clm. and degree.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 10:03
S38 9	1	S375 and ((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and (melting near10 (lower or higher or greater)).clm. and (degree near5 (higher or lower or greater)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 10:03
S39 0	2	((melting adj (point or temperature)) near10 (solder or standoff)).clm. and ((melting adj (point or temperature)) near10 (contact or pad)).clm. and (melting near10 (lower or higher or greater)).clm. and (degree near5 (higher or lower or greater)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 10:04